

N-Channel Enhancement Mode MOSFET

1. Product Information

Features

Advanced Trench Technology
Excellent $R_{DS(ON)}$ and Low gate charge

Applications

Uninterruptible power supply
Power Factor Correction

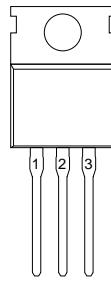
Quick reference

$V_{DS}=250$ V
 $I_D=50$ A
 $R_{DS(ON)} \leq 85$ mΩ @ $V_{GS}=10$ V (Type: 70 mΩ)

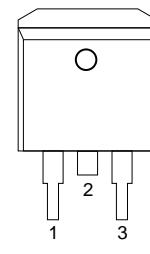
Pin Description

Pin	Description
1	Gate (G)
2	Drain (D)
3	Source (S)

Simplified Outline

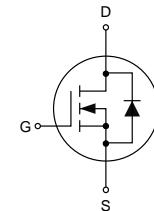


TO-220



TO-263

Symbol



Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape Width	Quantity
KJ50N25C	TO-220	KJ50N25C	-	-	1000
KJ50N25D	TO-263	KJ50N25D	-	-	800

2. Absolute Maximum Ratings ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Values	Unit
V_{DS}	Drain-Source Voltage	250	V
V_{GS}	Gate-Source Voltage	± 30	V
I_D	Continuous Drain Current	50	A
I_{DM}	Pulsed Drain Current	180	A
E_{AS}	Single Pulse Avalanche Energy	973	mJ
I_{AS}	Avalanche Current	36	A
E_{AR}	Repetitive Avalanche Energy	584	mJ
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	65	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55~150	°C
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Steady State) ¹	62.5	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-Case	1.6	°C/W

3. Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=250 \mu\text{A}$	250	275	-	V
$V_{\text{GS(th)}}$	Gate-Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250 \mu\text{A}$	2.0	3.0	4.0	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=250 \text{ V}, V_{\text{GS}}=0 \text{ V}$	-	-	1	μA
I_{GSS}	Gate-body Leakage current	$V_{\text{DS}}=0 \text{ V}, V_{\text{GS}}=\pm 30 \text{ V}$	-	-	± 100	nA
$R_{\text{DS(on)}}$	Drain-Source on-Resistance	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=22.5 \text{ A}$	-	70	85	$\text{m}\Omega$
C_{iss}	Input Capacitance	$V_{\text{DS}}=25 \text{ V}, V_{\text{GS}}=0 \text{ V}, f=1.0 \text{ MHz}$	-	3541	-	pF
C_{oss}	Output Capacitance		-	536	-	
C_{rss}	Reverse Transfer Capacitance		-	310	-	
Q_g	Total Gate Charge	$V_{\text{GS}}=10 \text{ V}, V_{\text{DD}}=200 \text{ V}, I_{\text{D}}=45 \text{ A}$	-	245	-	nC
Q_{gs}	Gate-Source Charge		-	17	-	
Q_{gd}	Gate-Drain Charge		-	141	-	
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=125 \text{ V}, I_{\text{D}}=45 \text{ A}, R_{\text{G}}=25 \Omega$	-	56	-	ns
t_r	Turn-on Rise Time		-	147	-	
$t_{\text{d(off)}}$	Turn-off Delay Time		-	958	-	
t_f	Turn-off Fall Time		-	241	-	
I_s	Continuous Body Diode Current		-	-	45	A
I_{SM}	Pulsed Diode Forward Current		-	-	180	A
V_{SD}	Body Diode Voltage	$I_{\text{SD}}=22.5 \text{ A}, V_{\text{GS}}=0 \text{ V}$	-	-	1.4	V
t_{rr}	Reverse Recovery Time	$V_{\text{GS}}=10 \text{ V}, I_s=10 \text{ A}, dI_F/dt=100 \text{ A}/\mu\text{s}$	-	266	-	ns
Q_{rr}	Reverse Recovery Charge		-	3	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2 OZ copper.
2. The E_{AS} data shows Max. rating. $I_{\text{AS}}=36 \text{ A}, V_{\text{DD}}=50 \text{ V}, R_{\text{G}}=25 \Omega$, Starting $T_J=25^\circ\text{C}$
3. The test condition is Pulse Test: Pulse width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 1\%$.
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I_{D} and I_{DM} , in real applications, should be limited by total power dissipation.

4.Typical Characteristics

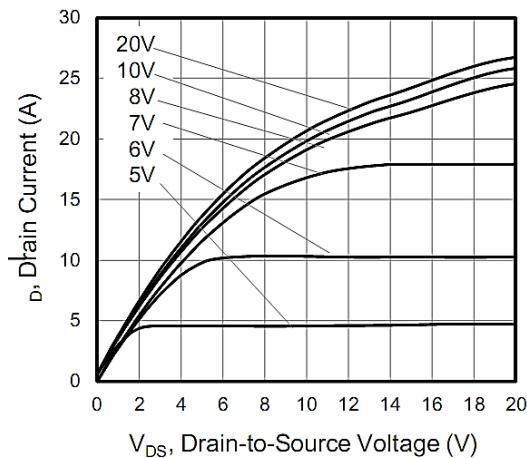


Figure 1. Output Characteristics

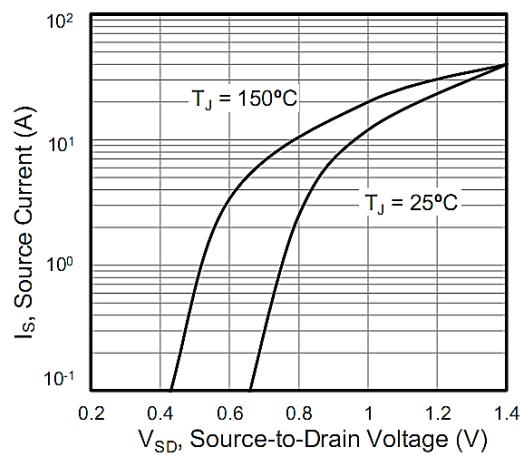


Figure 2. Body Diode Forward Voltage

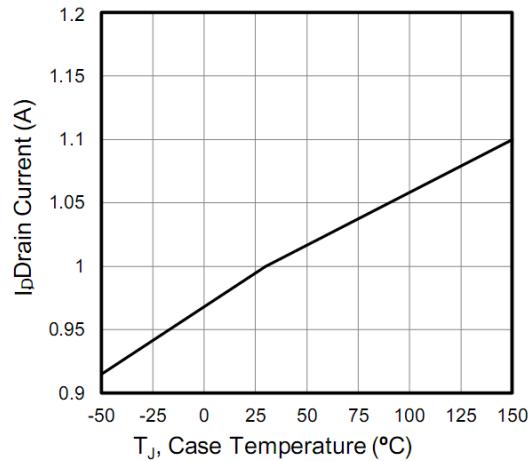


Figure 3. Drain Current vs. Temperature

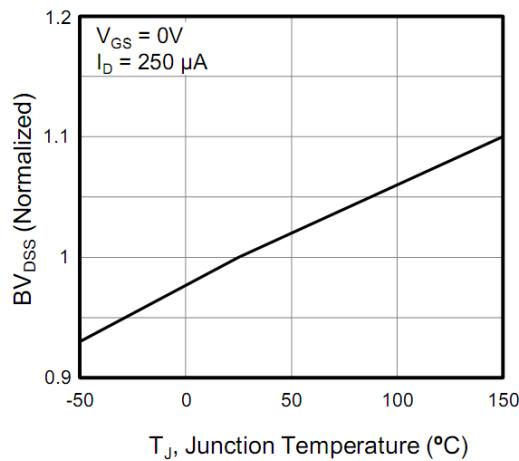


Figure 4. BV_{DSS} Variation vs. Temperature

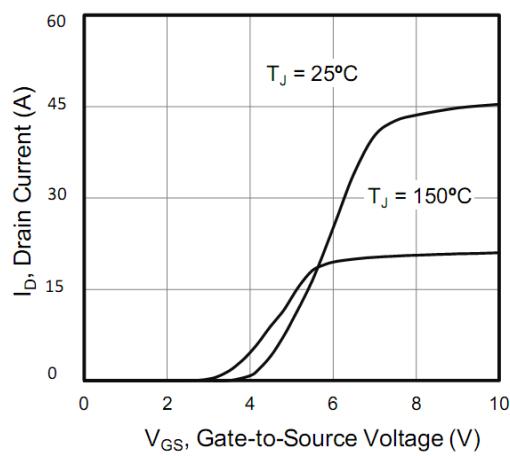


Figure 5. Transfer Characteristics

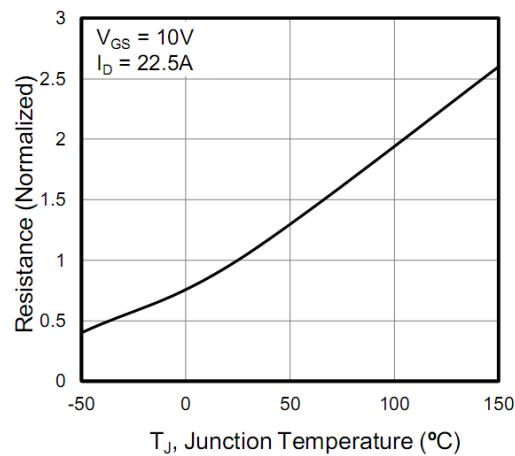


Figure 6. On-Resistance vs. Temperature

4.Typical Characteristics (Cont.)

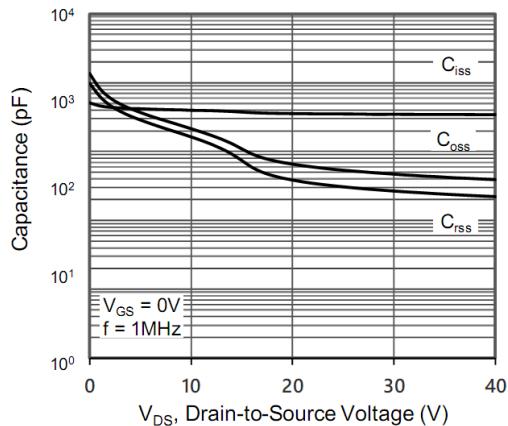


Figure 7. Capacitance

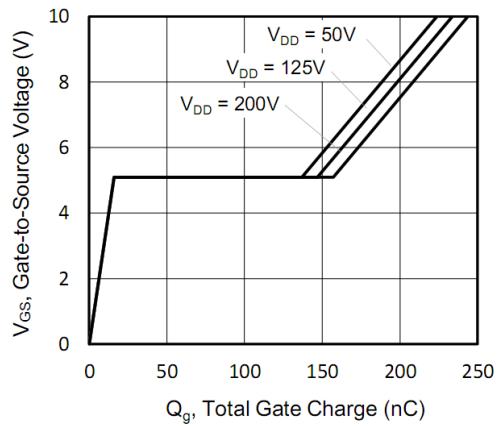


Figure 8. Gate Charge

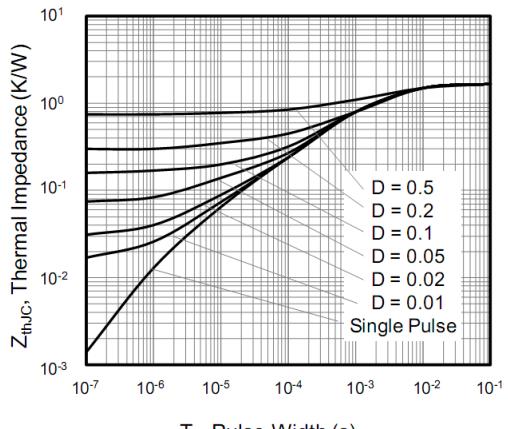
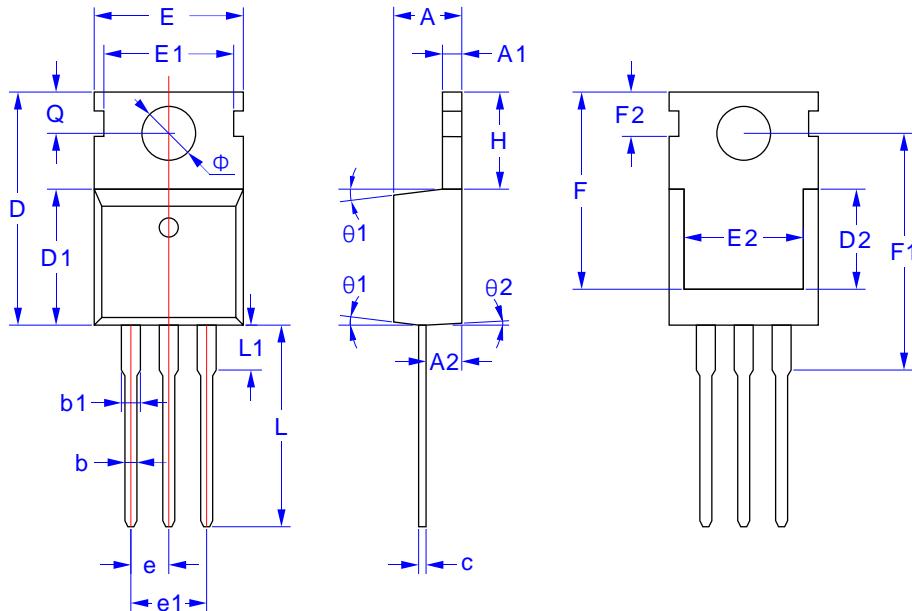


Figure 9. Transient Thermal Impedance

5. Package Mechanical Data

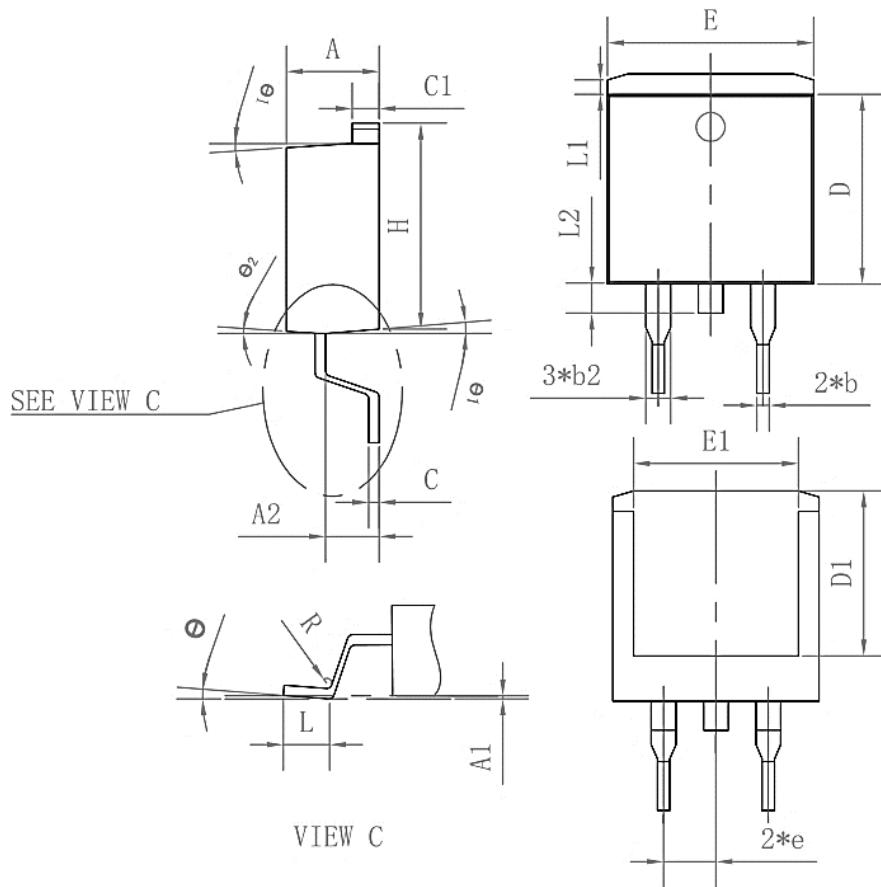
TO-220 Package



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	4.27	4.57	4.87	0.1681	0.1799	0.1917
A1	1.15	1.30	1.45	0.0453	0.0512	0.0571
A2	2.10	2.40	2.70	0.0827	0.0945	0.1063
b	0.70	0.80	1.00	0.0276	0.0315	0.0394
b1	1.17	1.27	1.50	0.0461	0.0500	0.0591
c	0.40	0.50	0.65	0.0157	0.0197	0.0256
D	15.50	15.80	16.10	0.6102	0.6220	0.6339
D1	8.80	9.10	9.40	0.3465	0.3583	0.3701
D2	5.70	6.70	7.00	0.2244	0.2638	0.2756
E	9.70	10.00	10.30	0.3819	0.3937	0.4055
E1	-	8.70	-	-	0.3425	-
E2	7.00	8.00	8.40	0.2756	0.3150	0.3307
e	2.54			0.1000		
e1	5.08			0.2000		
F	13.30	13.50	13.70	0.5236	0.5315	0.5394
F1	15.50	15.90	16.30	0.6102	0.6260	0.6417
F2	2.80	3.00	3.20	0.1102	0.1181	0.1260
H	6.00	6.50	6.85	0.2362	0.2559	0.2697
L	12.75	13.50	13.90	0.5020	0.5315	0.5472
L1	-	3.10	3.40	-	0.1220	0.1339
Q	2.60	2.80	3.00	0.1024	0.1102	0.1181
Φ	3.45	3.60	3.75	0.1358	0.1417	0.1476
θ1	4°	7°	10°	4°	7°	10°
θ2	0°	3°	6°	0°	3°	6°

5. Package Mechanical Data

TO-263 Package



Symbol	Dimensions in Millimeters		
	Mim	Nom	Max
A	4.35	4.47	4.60
A1	0.09	0.10	0.11
A2	2.30	2.40	2.70
b	0.70	0.80	1.00
b2	1.25	1.36	1.50
C	0.45	0.50	0.65
C1	1.29	1.30	9.40
D	9.10	9.20	9.30
D1	7.90	8.00	8.10
E	9.85	10.00	10.20
E1	7.90	8.00	8.10
H	15.30	15.50	15.70
e	-	2.54	-
L	2.34	2.54	2.74
L1	1.00	1.10	1.20
L2	1.30	1.40	1.50
R	0.24	0.25	0.26
θ	0°	4°	8°
θ_1	4°	7°	10°
θ_2	0°	3°	6°